

## Abstract

### CMP Process

The optimization of a CMP process provides the use of an auxiliary layer (4) between a dielectric (1) in the vicinity of patterned portions and a layer of a liner (2). If the liner (2) is perforated in the CMP process, then the undercutting of the liner (2) by the chemical removal of the auxiliary layer (4) simplifies the process overall. Advantages are significantly lower defect densities due to CMP scratches, fewer short circuits, fewer alignment errors.

Figure 1

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